

HiPerFET™ Power MOSFETs Q-Class

N-Channel Enhancement Mode
Avalanche Rated, Low Q_g , High dv/dt

IXFN 73N30Q

V_{DSS} = 300 V
 I_{D25} = 73 A
 $R_{DS(on)}$ = 45 mΩ

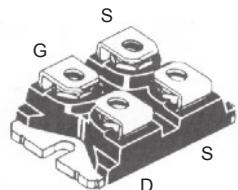
$t_{rr} \leq 250$ ns



Preliminary data sheet

Symbol	Test Conditions	Maximum Ratings		
V_{DSS}	$T_J = 25^\circ\text{C}$ to 150°C	300	V	
V_{DGR}	$T_J = 25^\circ\text{C}$ to 150°C ; $R_{GS} = 1\text{ M}\Omega$	300	V	
V_{GS}	Continuous	± 30	V	
V_{GSM}	Transient	± 40	V	
I_{D25}	$T_c = 25^\circ\text{C}$	73	A	
I_{DM}	$T_c = 25^\circ\text{C}$, pulse width limited by T_{JM}	292	A	
I_{AR}	$T_c = 25^\circ\text{C}$	73	A	
E_{AR}	$T_c = 25^\circ\text{C}$	60	mJ	
E_{AS}		2.5	J	
dv/dt	$I_s \leq I_{DM}$, $di/dt \leq 100\text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DSS}$, $T_J \leq 150^\circ\text{C}$, $R_G = 2\Omega$	10	V/ns	
P_D	$T_c = 25^\circ\text{C}$	500	W	
T_J		-55 to +150	°C	
T_{JM}		150	°C	
T_{stg}		-55 to +150	°C	
V_{ISOL}	50/60 Hz, RMS $t = 1\text{ min}$ $I_{ISOL} \leq 1\text{ mA}$ $t = 1\text{ s}$	2500 3000	V~	
M_d	Mounting torque Terminal connection torque	1.5/13 1.5/13	Nm/lb.in.	
Weight		30	g	

miniBLOC, SOT-227 B (IXFN)
 E153432



G = Gate
S = Source

Either Source terminal at miniBLOC can be used as Main or Kelvin Source

Features

- IXYS advanced low Q_g process
- Low gate charge and capacitances
 - easier to drive
 - faster switching
- Unclamped Inductive Switching (UIS) rated
- Low $R_{DS(on)}$
- Fast intrinsic diode
- International standard package
- miniBLOC with Aluminium nitride isolation for low thermal resistance
- Low terminal inductance (<10 nH) and stray capacitance to heatsink (<35pf)
- Molding epoxies meet UL 94 V-0 flammability classification

Applications

- DC-DC converters
- Battery chargers
- Switched-mode and resonant-mode power supplies
- DC choppers
- Temperature and lighting controls

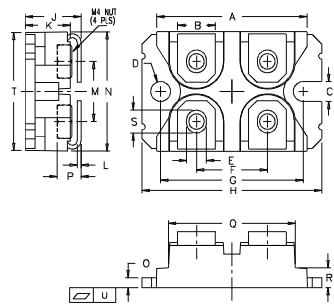
Advantages

- Easy to mount
- Space savings
- High power density

Symbol	Test Conditions	Characteristic Values		
		($T_J = 25^\circ\text{C}$, unless otherwise specified)	min.	typ.
V_{DSS}	$V_{GS} = 0\text{ V}$, $I_D = 1\text{ mA}$	300		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 4\text{ mA}$	2.0	4.0	V
I_{GSS}	$V_{GS} = \pm 20\text{ V}_{DC}$, $V_{DS} = 0$		± 100	nA
I_{DSS}	$V_{DS} = V_{DSS}$ $V_{GS} = 0\text{ V}$	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$	25 2	μA mA
$R_{DS(on)}$	$V_{GS} = 10\text{ V}$, $I_D = 0.5 I_{D25}$ Pulse test, $t \leq 300\text{ }\mu\text{s}$, duty cycle $d \leq 2\%$		45	mΩ

Symbol	Test Conditions	Characteristic Values		
		($T_J = 25^\circ\text{C}$, unless otherwise specified)	min.	typ.
g_{fs}	$V_{DS} = 10 \text{ V}; I_D = 0.5 \cdot I_{D25}$, pulse test	30	55	S
C_{iss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	5400	pF	
C_{oss}		1300	pF	
C_{rss}		370	pF	
$t_{d(on)}$	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$ $R_G = 1.0 \Omega$ (External),	37	ns	
t_r		36	ns	
$t_{d(off)}$		82	ns	
t_f		12	ns	
$Q_{g(on)}$	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$	195	nC	
Q_{gs}		42	nC	
Q_{gd}		82	nC	
R_{thJC}			0.22	K/W
R_{thCK}			0.05	K/W

Symbol	Test Conditions	Characteristic Values		
		($T_J = 25^\circ\text{C}$, unless otherwise specified)	min.	typ.
I_s	$V_{GS} = 0 \text{ V}$		73	A
I_{SM}	Repetitive; pulse width limited by T_{JM}		292	A
V_{SD}	$I_F = I_s, V_{GS} = 0 \text{ V}$, Pulse test, $t \leq 300 \mu\text{s}$, duty cycle $d \leq 2 \%$		1.5	V
t_{rr}	$I_F = 25 \text{ A}, -di/dt = 100 \text{ A}/\mu\text{s}, V_R = 100 \text{ V}$	0.8	250	ns
Q_{RM}		7	μC	
I_{RM}			A	

miniBLOCS, SOT-227 B


M4 screws (4x) supplied

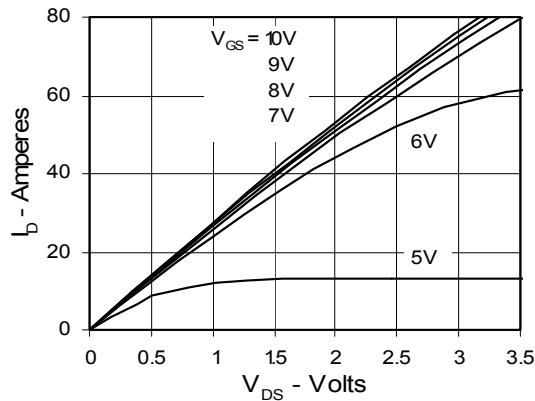
Dim.	Millimeter Min.	Millimeter Max.	Inches Min.	Inches Max.
A	31.50	31.88	1.240	1.255
B	7.80	8.20	0.307	0.323
C	4.09	4.29	0.161	0.169
D	4.09	4.29	0.161	0.169
E	4.09	4.29	0.161	0.169
F	14.91	15.11	0.587	0.595
G	30.12	30.30	1.186	1.193
H	38.00	38.23	1.496	1.505
J	11.68	12.22	0.460	0.481
K	8.92	9.60	0.351	0.378
L	0.76	0.84	0.030	0.033
M	12.60	12.85	0.496	0.506
N	25.15	25.42	0.990	1.001
O	1.98	2.13	0.078	0.084
P	4.95	5.97	0.195	0.235
Q	26.54	26.90	1.045	1.059
R	3.94	4.42	0.155	0.174
S	4.72	4.85	0.186	0.191
T	24.59	25.07	0.968	0.987
U	-0.05	0.1	-0.002	0.004

IXYS reserves the right to change limits, test conditions, and dimensions.

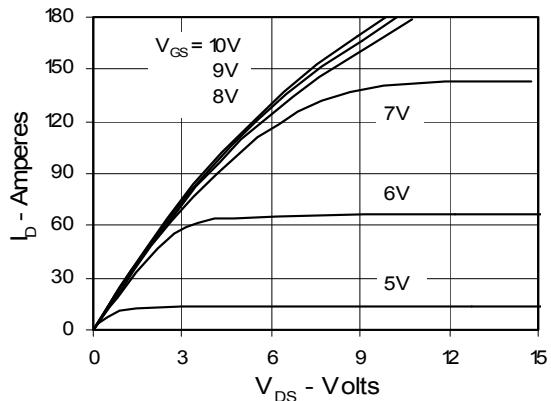
IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:
4,835,592 4,881,106 5,017,508 5,049,961 5,187,117 5,486,715 6,306,728B1 6,259,123B1 6,306,728B1
4,850,072 4,931,844 5,034,796 5,063,307 5,237,481 5,381,025 6,404,065B1 6,162,665 6,534,343 6,583,505

Fig. 1. Output Characteristics

@ 25 Deg. C

**Fig. 2. Extended Output Characteristics**

@ 25 deg. C

**Fig. 3. Output Characteristics**

@ 125 Deg. C

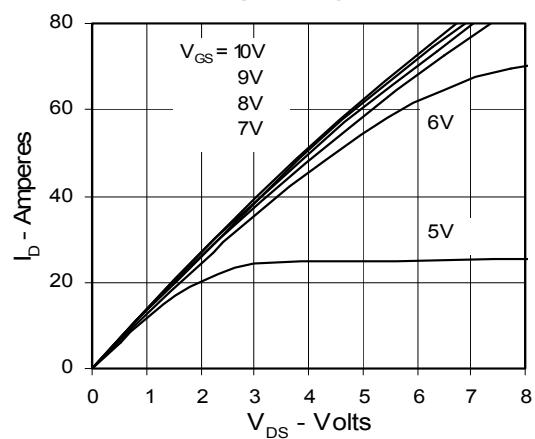
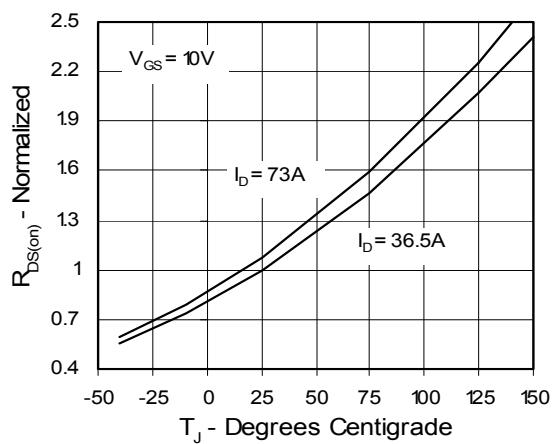
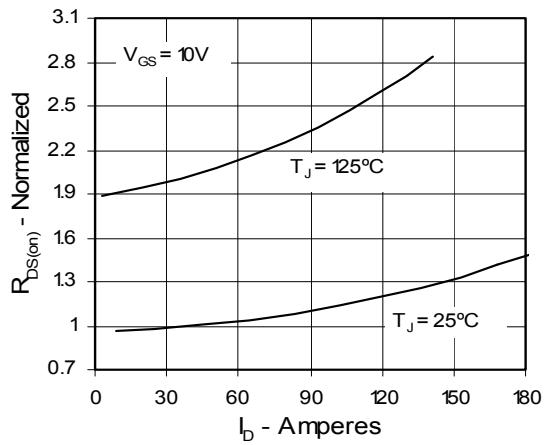
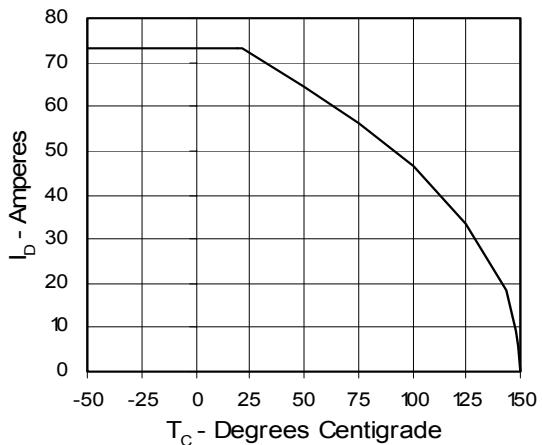
**Fig. 4. $R_{DS(on)}$ Normalized to I_{D25} Value vs. Junction Temperature****Fig. 5. $R_{DS(on)}$ Normalized to I_{D25} Value vs. I_D** **Fig. 6. Drain Current vs. Case Temperature**

Fig. 7. Input Admittance

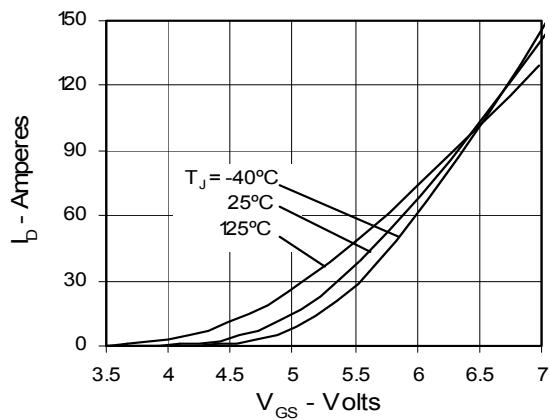


Fig. 8. Transconductance

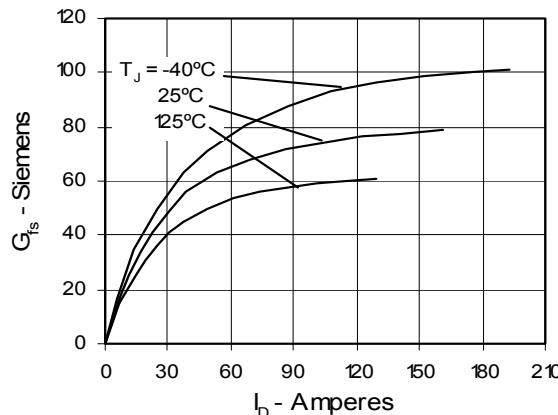


Fig. 9. Source Current vs. Source-To-Drain Voltage

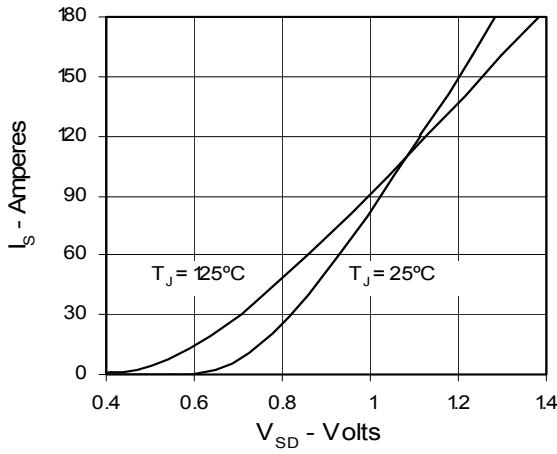


Fig. 10. Gate Charge

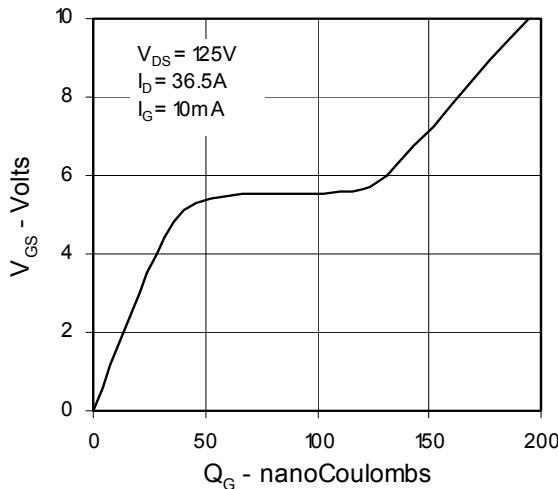


Fig. 11. Capacitance

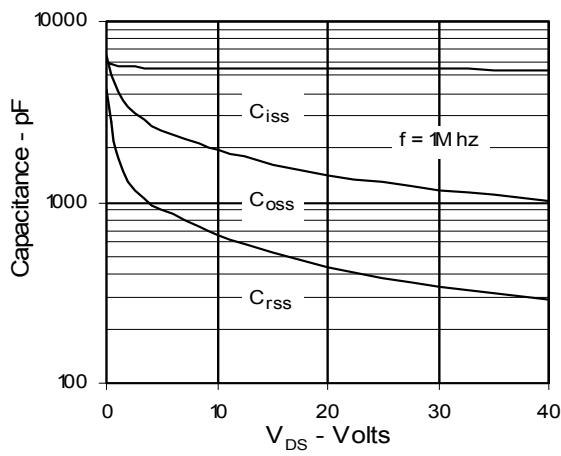
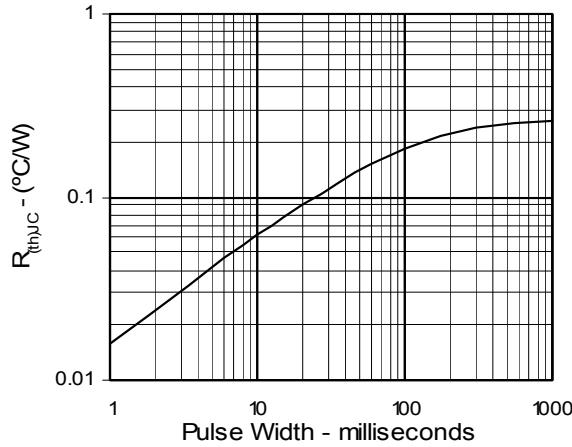


Fig. 12. Maximum Transient Thermal Resistance



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